

# XDR™ DRAM Code Information(1/2)

Last Updated : February 2008

**K** **4** X X X X X X X X - X X X X X X X  
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

## 1. Memory (K)

2. DRAM : 4

## 3. Small Classification

Y : XDR™ DRAM

## 4~5. Density, Refresh

50 : 512M, 32K/16ms

## 6~7. Organization

02 : x2

04 : x4

08 : x8

16 : x16

## 8. Bank

4 : 8Banks

## 9. Interface, VDD, VDDQ

U : DRSL, 1.8V, 1.2V

## 10. Generation

11. "—"

## 12. Package

J : FBGA (Lead Free)

## 13. Temp, Power

C : Commercial, Normal

## 14~15. Speed (Data frequency, tRAC, tRC)

DS : Daisychain Sample

A2 : 2.4Gbps, 36ns, 16cycles

B3 : 3.2Gbps, 35ns, 20cycles

C3 : 3.2Gbps, 35ns, 24cycles

C4 : 4.0Gbps, 28ns, 24cycles

# XDR™ DRAM Code Information(2/2)

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<u>K</u>	<u>4</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>-</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17 18

## 16. Packing “Packing Type Reference”

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
<b>Component</b>	TAPE & REEL	T
	Other ( Tray, Tube, Jar )	0 ( Number)
<b>Module</b>	MODULE TAPE & REEL	P
	MODULE Other Packing	M

## 17~18. Customer “Customer List Reference”